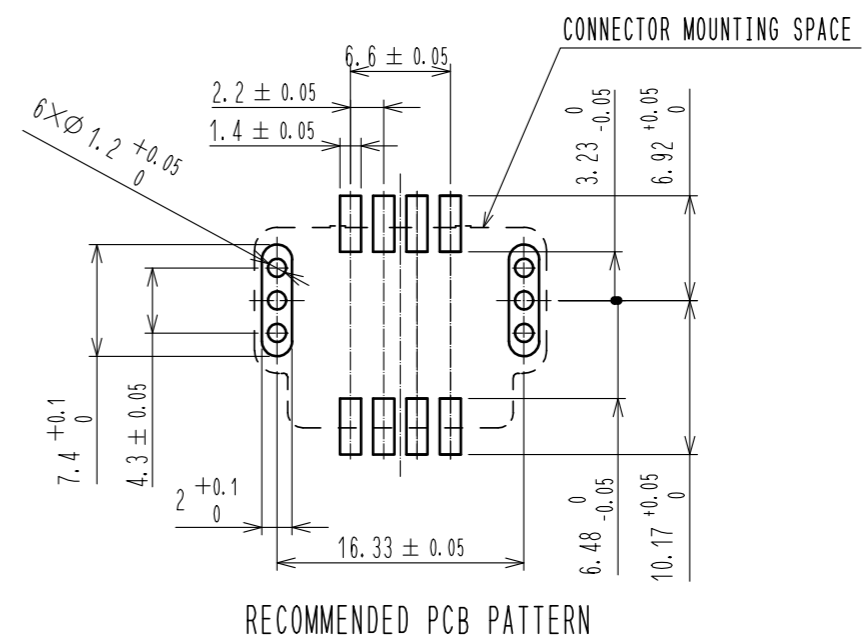
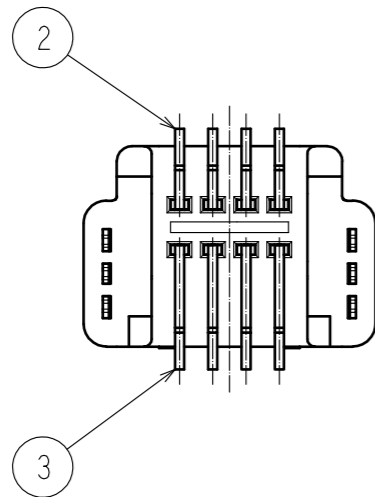
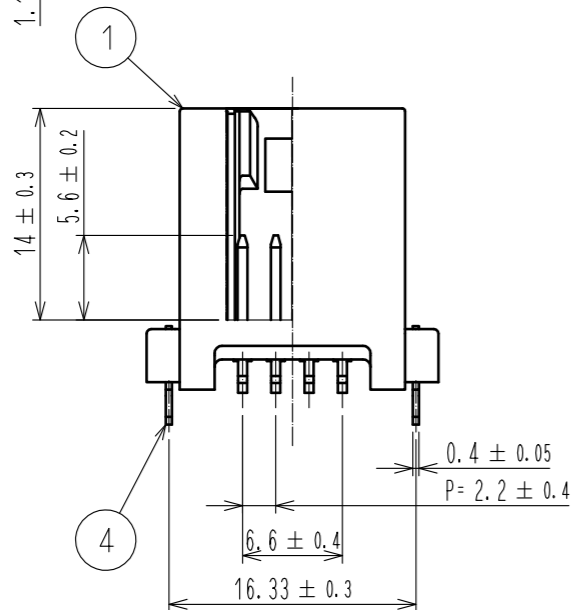
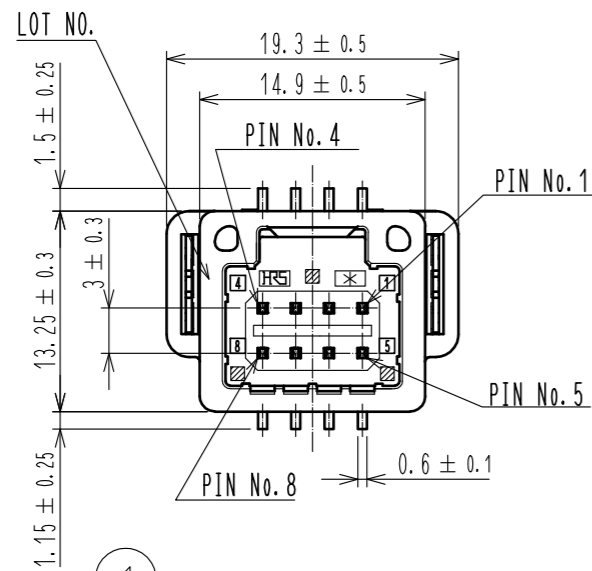
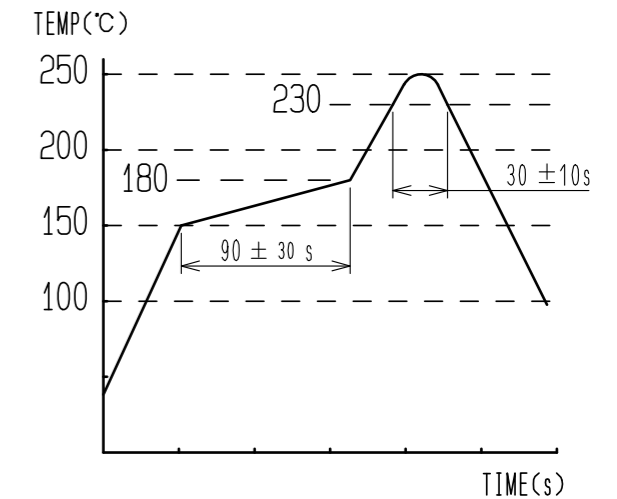


ELV, RoHS COMPLIANT



HRS DRAWING FOR REFERENCE

- NOTE 1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW (REFER TO RIGHT FIG.) USED REFLOW SYSTEM
- : IR IN THE AIR OR NITROGEN
 - NO. OF CYCLES : 2 MAX
 - PEAK : 250°C
 - OVER 230°C : 20~40s
 - PREHEAT : 150~180°C
 - 60~120s
 - 2. TEMPERATURE FOR SOLDERING IRON : 280~300°C WITHIN 2s
 - 3. CO-PLANARITY SHALL BE 0.1mm MAX.
 - 4. RECOMMENDED PCB THICKNESS IS 1.6mm.
 - 5. RECOMMENDED SOLDER THICKNESS IS 0.15mm.



2	BRASS	TIN PLATED T=0.64	4	BRASS	TIN PLATED T=0.4
1	PPS	BLACK	3	BRASS	TIN PLATED T=0.64
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS	mm	SCALE	2 : 1	COUNT	DESCRIPTION OF REVISIONS
		APPROVED	: NH. NAKATA	15.10.28	DRAWING NO.
		CHECKED	: HS. OZAWA	15.10.28	PART NO.
		DESIGNED	: TK. SHISHIKURA	15.10.28	CODE NO.
		DRAWN	: TK. SHISHIKURA	15.10.28	CL775-0094-0-00
				DESIGNED	
				CHECKED	
				DATE	
				EDC-364861-00-00	
				GT25H2-8DP-2.2V	
				1/1	